

RoHS

MAPX

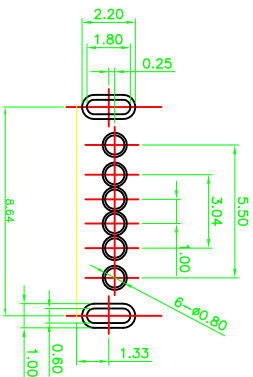
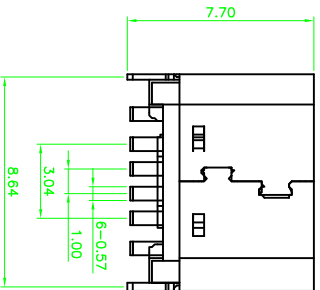
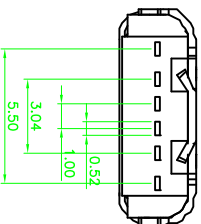
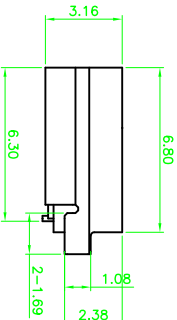
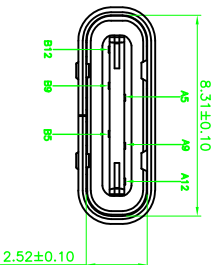
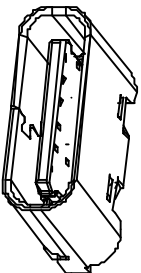
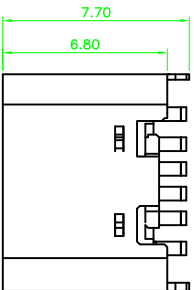
MODIFICATION

DRW

DATE

NOTE:

1. MATERIAL SPECIFICATION
1. HOUSING : HIGH TEMPERATURE RESISTANT PLASTIC UL94 V-0
2. CONTACTS : COPPER ALLOY
3. MID PLATE : STAINLESS STEEL
4. FRONT SHELL : STAINLESS STEEL
2. PLATING SPECIFICATION
- 2-1. CONTACTS :
Ni 50u " MIN. UNDER PLATED OVER ALL.
Au PLATED ON THE FUNCTIONAL AREA OF CONTACT
(GOLD PLATING THICKNESS FOLLOW THE P / N)
PLATING SPECIFICATIONS OF THE SOLDER AREA FOLLOW THE P / N
- 2-2. FRONT SHELL . SEE TABLE1
- 2-3 SHIELD PLATE & EMI PLATE CLEAR ONLY
3. MECHANICAL PERFORMANCE.
- 3-1. INSERTION FORCE : 0.5~2.0 kgf.
- 3-2. REMOVAL FORCE . 0.8kgf ~2.0Kgf
- 3-3 DURABILITY : 5000 CYCLES .
4. ELECTRICAL PERFORMANCE ,
- 4-1 . CURRENT RATING : 3 . 0A VOLTAGE RATING . 5.0V
- 4-2 . ILCCR .
- VBUS GND PINS AND OTHER PINS : 40m / PIN MAX
SHIELD : 50mq / MAX
ILCCR MAX. CHANGE OF ALL PINS : 10m Ω
- 4-3. INSULATION RESISTANCE : 100MΩ MIN
- 4-4 DIELECTRIC WITHSTAND VOLTAGE , AC 100V FOR 1 MINUTE .
5. ENVIRONMENTAL PERFORMANCE
- OPERATING TEMPERATURE : -25C . + 85C
6. IR REFLOW
THE PEAK TEMPERATURE ON THE BOARD SHALL
BE MAINTAINED FOR 10 SECONDS AT 260C .



RECOMMENDED PCB LAYOUT
TOLERANCE UNSPECIFIED ±0.05mm

B12	GND
B9	VBUS
B5	CC2
A5	CC1
A9	VBUS
A12	GND
PIN	SIGNAL NAME

产品图

公差一览表			
TOLERANCE	UNLESS OTHERWISE	UNIT	
X.	±0.25	X.	±5°
X	±0.20	X	±2°
.XX	±0.15	.XX	±1°
.XXX	±0.10	.XXX	±0.5°

深圳市精拓金电子有限公司
Shenzhen Jing Tuo Jin Electronics Co., Ltd.

单位	UNIT	制图	制图料号
比例	SCALE	审核	产品名称
日期	DATE	核准	角法
XXX	±0.10	.XXX	±0.5°